

CHONGQING CLOUDCHILD TECHNOLOGY CO., LTD

DBS Plastic-Encapsulate Bridge Rectifier

DB101S-DB107S Bridge Rectifier

Features

- I₀ 1A
- V_{RRM} 50V-1000V
- High surge current capability
- Glass passivated chip
- Polarity:Color band denotes cathode
- AEC Q101 Qualified

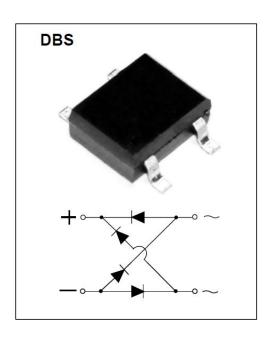
Applications

General purpose 1 phase Bridge rectifier applications

MARKING

DB10XS

X: From 1 To 7



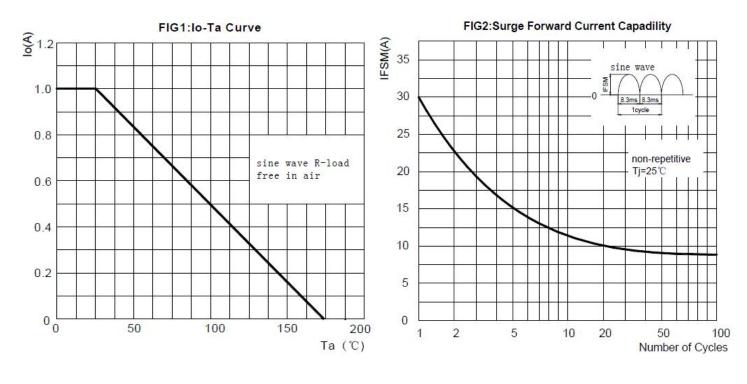
ABSOLUTE MAXIMUM RATINGS (T_a=25℃ unless otherwise noted)

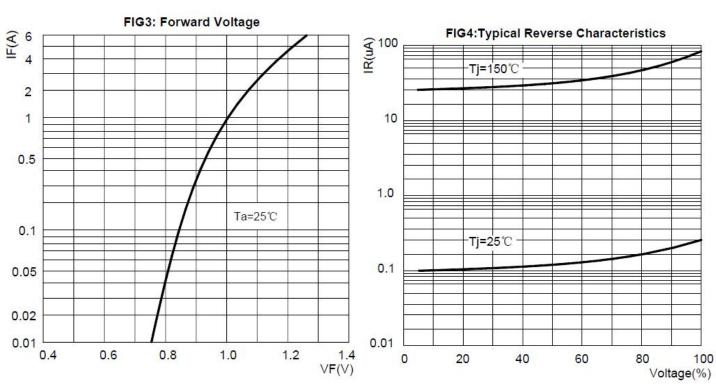
Item	Symbol	Unit	Conditions			DB1						
					01S	02S	03S	048	05S	06S	07S	
Repetitive Peak Reverse Voltage	V _{RRM}	٧			50	100	200	400	600	800	1000	
Maximum RMS Voltage	V _{RMS}	V			35	70	140	280	420	560	700	
Average Rectified Output Current	lo	А	60Hz sine wave, R- load,Ta=25℃	On glass-epoxi substrate	1							
Surge(Non- repetitive)Forward Current	I _{FSM}	А	60H _z sine wave, 1 cycle, T _j =25℃			30						
Current Squared Time	l²t	A ² S	1ms≤t<8.3ms Tj=25℃,Rating of per diode			3.7						
Storage Temperature	T _{stg}	$^{\circ}$			-55 ~+175							
Junction Temperature	Tj	$^{\circ}$			-55 ~+175							

ELECTRICAL CHARACTERISTICS (T_a =25 $^{\circ}$ C unless otherwise noted)

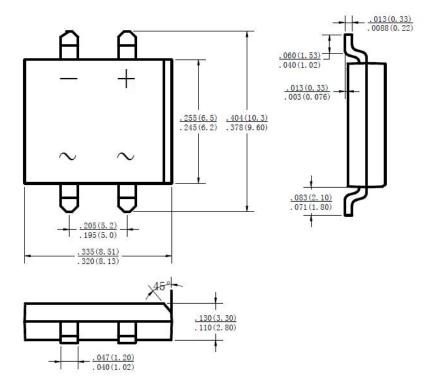
Item	Symbol	Unit	Test Condition	Max
Peak Forward Voltage	V_{FM}	V	I _{FM} =0.5A, Pulse measurement, Rating of per diode	1.05
Peak Reverse Current	I _{RRM}	μ Α	$V_{\text{RM}}\!\!=\!\!V_{\text{RRM}}$, Pulse measurement, Rating of per diode	10
	R θ J-A		Between junction and ambient, On glass-epoxi substrate	68
Thermal Resistance	R o J-L	°C/W	Between junction and lead	15

Typical Electrical and Thermal Characteristics



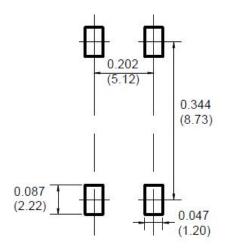


DBS Package Outline Dimensions



Dimensions in inches and (millimeters)

DBS Suggested Pad Layout



Note:

- 1.Controlling dimension:in millimeters.
- 2.General tolerance: ± 0.05mm.
- 3. The pad layout is for reference purposes only.

NOTICE

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